

AMENDMENTS TO THE CLAIMS:

Please amend Claims 1, 9, and 10 as follows:

1. (Currently Amended) A solid state image pick-up device formed on a chip, comprising:

a pixel region;

horizontal scanning circuits arranged along sides of the chip sandwiching the pixel region for reading a signal charge from the pixel region;

a vertical scanning circuit arranged along a side of the chip not parallel to a side of the chip along which a horizontal scanning circuit, of the horizontal scanning circuits, is arranged, wherein the vertical scanning circuit has a lower driving frequency than that of the horizontal scanning circuits;

an amplifier for amplifying the signal charge read from the pixel region by the horizontal scanning circuits, outputting video signals; **and**

a pad for outputting the video signals to an outside of the chip, the pad **for outputting the video signals** being arranged along a side of the chip along which none of the horizontal scanning circuits and the vertical scanning circuit is arranged; **and**

a pad being supplied with a signal for driving a horizontal scanning circuit of horizontal scanning circuits, the pad being supplied with the signal for driving the horizontal scanning circuit being arranged only along a side of the chip along which the horizontal scanning circuit is arranged.

2. (Previously Presented) The solid state image pick-up device according to claim 1, wherein in the pixel region, pixels having an active element are two-dimensionally arranged.

3. (Previously Presented) The solid state image pick-up device according to claim 2, wherein the active element comprises at least one selected from the group consisting of a transfer MOS transistor, a reset MOS transistor, a source follower input MOS transistor, and a selection MOS transistor.

4. (Cancelled)

5. (Previously Presented) The solid state image pick-up device according to claim 2, wherein the pixel region is formed into a rectangle, and the horizontal scanning circuits are arranged closer to a long side of the pixel region.

6 - 7. (Cancelled)

8. (Original) A camera, comprising:  
the solid state image pick-up device according to claim 1;  
a lens for forming an optical image of a subject; and  
a signal processing unit for processing a signal from the solid state image pick-up device.

9. (Currently Amended) A solid state image pick-up device formed on a chip, comprising:  
a pixel region;  
horizontal scanning circuits arranged along sides of the chip sandwiching the pixel region for reading a signal charge from the pixel region;  
a vertical scanning circuit arranged along a side of the chip not parallel to a side of the chip along which a horizontal scanning circuit, of the horizontal scanning

circuits, is arranged, wherein the vertical scanning circuit has a lower driving frequency than that of the horizontal scanning circuits;

an amplifier for amplifying the signal charge read from the pixel region by the horizontal scanning circuits, outputting video signals; and

a pad for supplying a voltage to the amplifier, the pad for supplying a voltage to the amplifier being arranged along a side of the chip along which none of the horizontal scanning circuits and the vertical scanning circuit is arranged; and

a pad being supplied with a signal for driving a horizontal scanning circuit of horizontal scanning circuits, the pad being supplied with the signal for driving the horizontal scanning circuit being arranged only along a side of the chip along which the horizontal scanning circuit is arranged

10. (Currently Amended) A solid state image pick-up device formed on a chip, comprising:

a pixel region;

horizontal scanning circuits arranged along sides of the chip sandwiching the pixel region for reading a signal charge from the pixel region;

a vertical scanning circuit arranged along a side of the chip not parallel to a side of the chip along which a horizontal scanning circuit, of the horizontal scanning circuits, is arranged, wherein the vertical scanning circuit has a lower driving frequency than that of the horizontal scanning circuits;

an amplifier for amplifying the signal charge read from the pixel region by the horizontal scanning circuits, outputting video signals; and

a pad for supplying a predetermined voltage or a ground voltage to an active element included in a pixel in the pixel region, the pad for supplying a predetermined

voltage or a ground voltage being arranged along a side of the chip along which none of the horizontal scanning circuits and the vertical scanning circuit is arranged; and

a pad being supplied with a signal for driving a horizontal scanning circuit of horizontal scanning circuits, the pad being supplied with the signal for driving the horizontal scanning circuit being arranged only along a side of the chip along which the horizontal scanning circuit is arranged

11. (Previously Presented) The solid state image pick-up device according to claim 1, wherein side portions along which the horizontal scanning circuits are arranged and a side portion along which the vertical scanning circuit is arranged are adjacent to each other.

12. (Previously Presented) The solid state image pick-up device according to claim 9, wherein side portions along which the horizontal scanning circuits are arranged and a side portion along which the vertical scanning circuit is arranged are adjacent to each other.

13. (Previously Presented) The solid state image pick-up device according to claim 10, wherein side portions along which the horizontal scanning circuits are arranged and a side portion along which the vertical scanning circuit is arranged are adjacent to each other.

14. (Previously Presented) The solid state image pick-up device according to claim 1, wherein the pad is arranged only along a side portion of the chip at an angle of 90 degrees to a side portion along which a horizontal scanning circuit, of the horizontal scanning circuits, is arranged.

15. (Previously Presented) The solid state image pick-up device according to claim 9, wherein the pad is arranged only along a side portion of the chip at an angle of 90 degrees to a side portion along which a horizontal scanning circuit, of the horizontal scanning circuits, is arranged.

16. (Previously Presented) The solid state image pick-up device according to claim 10, wherein the pad is arranged only along a side portion of the chip at an angle of 90 degrees to a side portion along which a horizontal scanning circuit, of the horizontal scanning circuits, is arranged.